

Abstract

A semiconductor device has a flex cable and a substrate attached to the flex cable. A first semiconductor die and a photonic semiconductor die are disposed over the flex cable opposite the substrate. The flex cable is deformed to attach the flex cable to a side surface of the photonic semiconductor die. A second semiconductor die is disposed over the substrate opposite the flex cable. An encapsulant is deposited over the second semiconductor die, substrate, and flex cable. An end of the flex cable remains extending from the encapsulant.

(Fig. 2j)